FOR USE AS LAMP, RELAY, OR MOS DRIVERS

- Full Decoding of Input Logic
- SN54145, SN74145, and SN74LS145 Have 80-mA Sink-Current Capability
- All Outputs Are Off for Invalid BCD Input Conditions
- Low Power Dissipation of 'LS145 . . .
 35 mW Typical

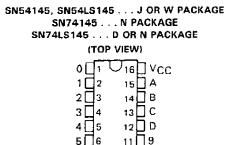
FUNCTION TABLE

NO.		INP	UTS					0	UTI	דטי	S			
190.	D	C	В	Α	0	1	2	3	4	5	6	7	8	9
0	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н
1	L	L	L	Н	H	L	Н	Н	Н	Н	Н	Н	Н	Н
2	L.	L.	н	L	н	Н	L	Н	Н	Н	н	н	Н	Н
3	L	L	Н	Н	н	H	Н	L	Н	Н	H	H	Н	н
4	Ł	Н	L	L	Н	Н	H	Н	L	H	H	H	Н	Н
5	Ł	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н	Н	н
6	L	Н	Н	L	н	Н	Н	Н	Н	Н	Ł	Н	Н	Н
7	L	H	Н	Н	Н	H	Н	Н	Н	Н	Н	L	Н	н
8	Н	L	L	L	Н	Н	Н	н	Н	Н	Н	Н	L	Н
9	Ι	L	L	Н	Н	Н	Н	н	Н	Н	Н	Н	н	L
	Н	L	Н	L	Н	H	Н	Н	Н	Н	Н	Н	Н	Н
ا ہ	H	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
=	н	H	L	L	Н	Н	Н	н	Н	н	Н	Н	Н	н
INVALID	Н	Н	L	Н	н	Н	Н	Н	Н	Н	Н	Н	Н	Н
=	Н	Н	Н	L	н	H	Н	Н	Н	Н	Н	Н	Н	н
	Н	Н	Н	H	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н

H = high level (off), L = low level (on)

description

These monolithic BCD-to-decimal decoder/drivers consist of eight inverters and ten four-input NAND gates. The inverters are connected in pairs to make BCD input data available for decoding by the NAND gates. Full decoding of valid BCD input logic ensures that all outputs remain off for all invalid binary input conditions. These decoders feature high-performance, n-p-n output transistors designed for use as indicator/relay drivers or as open-collector logic-circuit drivers. Each of the highbreakdown output transistors (15 volts) of the SN54145, SN74145, or SN74LS145 will sink up to 80 milliamperes of current. Each input is one Series 54/74 or Series 54LS/74LS standard load, respectively. Inputs and outputs are entirely compatible for use with TTL or DTL logic circuits, and the outputs are compatible for interfacing with most MOS integrated circuits. Power dissipation is typically 215 milliwatts for the '145 and 35 milliwatts for the 'LS145.

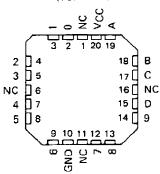


SN54LS145 . . . FK PACKAGE (TOP VIEW)

10 🗌 8

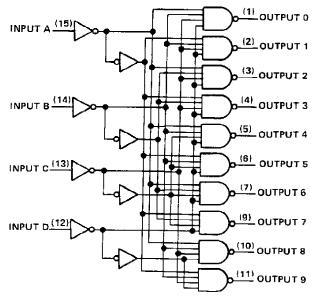
6 🗌 7

GND 18

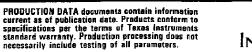


NC - No internal connection

logic diagram



Pin numbers shown are for D, J, N, and W packages.





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)							÷		-		-	-		7 V
Input voltage										-			5	5.5 V
Maximum current into any output (off-state)														
Operating free-air temperature range: SN54145	i ,				 								-55°C to 12	25°C
SN74145					 ÷								. 0°C to 7	70°C
Storage temperature range		_											-65°C to 15	50°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	:	SN5414	5		SN7414	5	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
Off-state output voltage, VO(off)			15			15	V
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDIT	IONS†	MIN	TYPİ	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage			<u> </u>		8.0	V
Vik	Input clamp voltage	V _{CC} = MIN, I _I = -12 mA				-1.5	V
IO(off)	Off-state output current	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, V _{Q(offl} = 15	v			250	μΑ
V _{Olon)}	On-state output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _H = 0.8 V	$I_{O(on)} = 80 \text{ mA}$ $I_{O(on)} = 20 \text{ mA}$		0.5	0.9 0.4	٧
11	Input current at maximum input voltage	VCC = MAX, V1 = 5.5 V	10(011)			1	mA
I _{IH}	High-level input current	V _{CC} = MAX, V ₁ - 2.4 V	· · · · · · · · · · · · · · · · · · ·			40	μA
III.	Low-level input current	V _{CC} = MAX, V _I = 0.4 V				-1.6	mA
1	Prophy acceptant	V -446V 0N	SN54145		43	62	
'cc	Supply current	V _{CC} = MAX, See Note 2	SN74145		43	70	mΑ

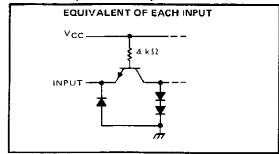
 $^{^\}dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at V_{CC} = 5 V, T_A = 25 °C. NOTE 2: I_{CC} is measured with all inputs grounded and outputs open.

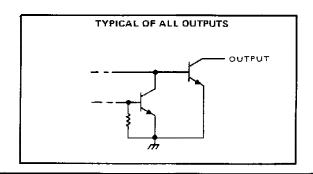
switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	L	TEST CONDITI	ONS	MIN	MAX	UNIT
tPLH Pr	opagation delay time, low-to-high-level output	Cı = 15 pF.	R ₁ = 100 Ω.	See Note 3		50	ns
tPHL Pr	opagation delay time, high-to-low-level output	CE - 19 pr.	H _L = 100 Ω,	266 IAQ16 2		50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

schematics of inputs and outputs





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1) .														7 V
Input voltage														
Operating free-air temperature range:	SN54LS145				 						- 5!	5°C	to	125°C
	SN74LS145				 							0°	C t	o 70°C
Storage temperature range					 						-6!	5°C	to	150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54LS145 SN74LS145	
	MIN NOM MAX MIN NOM M	X
Supply voltage, V _{CC}	4.5 5 5.5 4.75 5 5	25 V
Off-state output voltage, VO(off)	15	15 V
Operating free-air temperature, TA	-55 125 O	70 °C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONI	DITIONET	Si	N54LS1	45	SI	N74LS1	45	T
	ranameren	TEST COM	DITIONS	MIN	TYPİ	MAX	MIN	TYP‡	MAX	UNIT
۷ін	High-level input voltage		-	2			2			V
VIL	Low-level input voltage			† · · · · ·		0.7	<u> </u>		0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I ₁ = -18 mA			-1.5	-		-1.5	V
IQ(off)	Off-state output current	V _{CC} = MIN,	V _{IH} = 2 V,			250		~-	350	
-010111		VIL = VIL max,	V _{OH} = 15 V			200	}		250	μА
		VCC - MIN,	IOL = 12 mA		0.25	0.4		0.25	0.4	
VO(on)	On-state output voltage	V _{IH} ≈ 2 V,	I _{OL} = 24 mA					0.35	0.5	v
		VIL = VIL max	I _{OL} = 80 mA					2.3	3	
11	Input current at maximum input voltage	VCC = MAX.	V ₁ = 7 V			0.1			0.1	mA
Чн	High-level input current	V _{CC} = MAX,	V ₁ = 2.7 V			20			20	μA
II L	Law-level input current	V _{CC} = MAX,	V ₁ = 0.4 V		**	-0.4	-		-0.4	mA
Icc	Supply current	V _{CC} = MAX,	See Note 2		7	13		7	13	mΑ

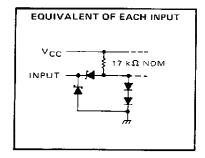
For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

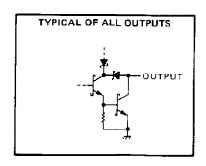
switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER		TEST CONDIT	ONS	MIN	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output	Ci = 45 pF.	D 665 O	See Note 3		50	ns
†PHL	Propagation delay time, high-to-low-level output	C[- 45 pF,	RL = 665 Ω,	TEE NOTE 2		50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

schematic of inputs and outputs





 $[\]stackrel{?}{+}$ All typical values are at V_{CC} = 5 V, T_A = 25°C. NOTE 2: I_{CC} is measured with all inputs grounded and outputs open.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8508401VEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8508401VE A SNV54LS145J	Samples
85084012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	85084012A SNJ54LS 145FK	Samples
8508401EA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8508401EA SNJ54LS145J	Samples
8508401FA	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8508401FA SNJ54LS145W	Samples
SN54LS145J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS145J	Samples
SN74145N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74145N	Samples
SN74LS145D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70	LS145	
SN74LS145DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS145	Samples
SN74LS145DRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS145	Samples
SN74LS145N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS145N	Samples
SN74LS145NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS145N	Samples
SN74LS145NSR	ACTIVE	SOP	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS145	Samples
SNJ54145J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54145J	Samples
SNJ54LS145FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	85084012A SNJ54LS 145FK	Samples
SNJ54LS145J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8508401EA SNJ54LS145J	Samples
SNJ54LS145W	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8508401FA SNJ54LS145W	Samples

 $^{^{(1)}}$ The marketing status values are defined as follows:

PACKAGE OPTION ADDENDUM

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ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54145, SN54LS145, SN54LS145-SP, SN74145, SN74LS145:

Catalog: SN74145, SN74LS145, SN54LS145

Military: SN54145, SN54LS145

Space: SN54LS145-SP

NOTE: Qualified Version Definitions:



PACKAGE OPTION ADDENDUM

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- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS145DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS145NSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS145DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74LS145NSR	SOP	NS	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE

INSTRUMENTS



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
85084012A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74145N	N	PDIP	16	25	506	13.97	11230	4.32
SN74145N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS145N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS145N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS145NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS145NE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS145FK	FK	LCCC	20	55	506.98	12.06	2030	NA

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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